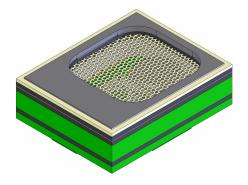


ULTRASONIC ACOUSTIC SENSOR





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1. DESCRIPTION AND APPLICATION

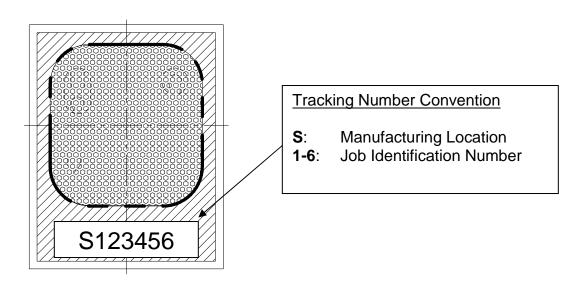
1.1. Description

Surface Mount Wide-Band Ultrasonic Acoustic Sensor

1.2. Applications

Hand held telecommunication devices, Positioning Sensing, Pneumatic Flow Sensing

2. PART MARKING



3. TEMPERATURE RANGE

3.1. Operating Temperature Range: -40°C to +100°C

3.2. Storage Temperature Range: -40°C to +100°C

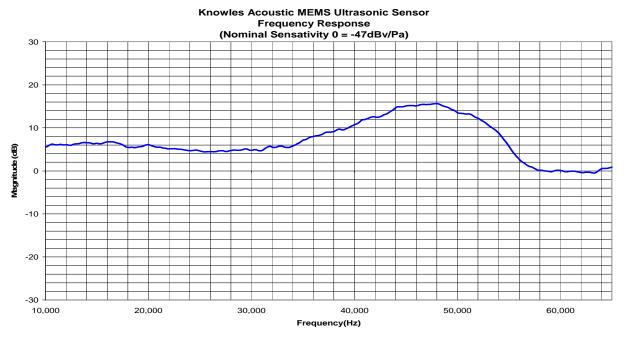




4. ACOUSTIC AND ELECTRICAL SPECIFICATIONS

| | Symbol | Condition | Limits | | Unit | |
|------------------------------------|----------|---|-----------------------------------|------|-------|---------|
| | Syllibol | Condition | Min. | Nom. | Max. | Offic |
| Directivity | | Omni-directional | | | | |
| Frequency Range | f | | 10k | | 65k | Hz |
| Sensitivity | S | @ 1kHz (0dB=1V/Pa) | -51 | -47 | -43 | dB |
| Output impedance | ZOUT | @ 1kHz (0dB=1V/Pa) | n/a | n/a | 300 | Ω |
| Current Consumption | IDSS | across 1.5 to 3.6 volts | 0.100 | n/a | 0.250 | mA |
| Signal to Noise Ratio | S/N | @ 1kHz (0dB=1V/Pa) | 55 | 59 | n/a | dB |
| Supply Voltage | Vs | | 1.5 | n/a | 3.6 | V |
| Typical Input Referred Noise | ENL | A-weighted | n/a | 35 | n/a | dBA SPL |
| Sensitivity Loss across Voltage | | Change in sensitivity over 3.6v to 1.5v | No Change Across Voltage Range | | dB | |
| Maximum Input Sound Level | | At 100dB SPL, At 115dB SPL, T | , | | dB | |

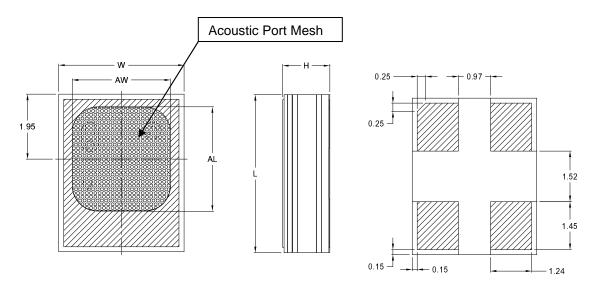
5. FREQUENCY RESPONSE CURVE







6. MECHANICAL SPECIFICATIONS



| <u>ltem</u> | <u>Dim.</u> | <u>Tol. (+/-)</u> | <u>Units</u> |
|---------------|-------------|-------------------|--------------|
| (H) Height | 1.40 | 0.10 | mm |
| (L) Length | 4.72 | 0.10 | mm |
| (W) Width | 3.76 | 0.10 | mm |
| Acoustic Area | | | |
| (AW) Width | 2.95 | - | mm |
| (AL) Length | 3.12 | - | mm |
| Weight | 0.07 | g | |
| Coplanarity | <0.1 | mm | |

| PIN Designation | | |
|-----------------|----------|--|
| Pin# | Function | |
| 1 | Output | |
| 2 | Ground | |
| 3 | Ground | |
| 4 | Power | |

Note:

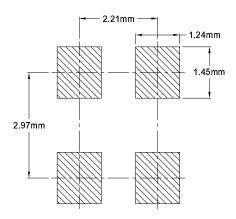
Special care must be used so that the Acoustic Port Mesh area is not touched or disturbed during application.

(Tolerance +/-0.15mm unless otherwise specified)

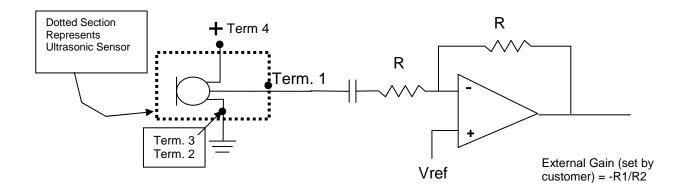




7. RECOMMENDED LAND PATTERN



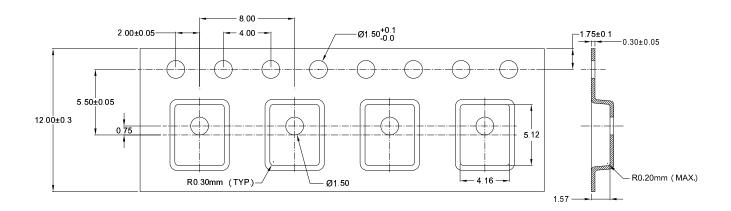
8. RECOMMENDED INTERFACE CIRCUIT







9. PACKAGE DETAIL



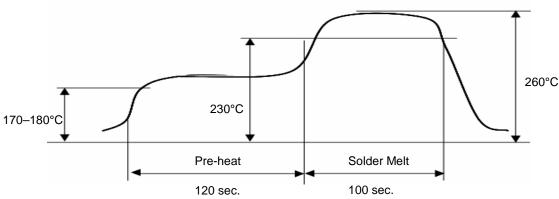
| Model Number | Suffix | <u>Reel</u> <u>Diameter</u> | Quantity per Reel |
|--------------|--------|--------------------------------|----------------------|
| SPM0204UD5 | -2 | 7" | 1,200 |
| SPM0204UD5 | -6 | 13" | 4,800 |

| Leader Length | 800mm or minimum of 100 empty pockets |
|------------------|---|
| Label | Label applied to external package and direct to reel. Per JEDEC. |
| Empty Units | No consecutive empty pockets; No more than 3 empty pockets per reel. (Does not include empty pockets for leader/follower) |





10. SOLDER REFLOW PROFILE



| <u>Stage</u> | <u>Temperature</u> <u>Profile</u> | <u>Time</u> (maximum) |
|--------------|--------------------------------------|--------------------------|
| Pre-heat | 170 ~ 180 C | 120 sec. |
| Solder Melt | Above 230 C | 100 sec. |
| Peak | 260 C maximum | 30 sec. |

Notes:

- <u>Do not pull a vacuum</u> over the port hole of the microphone.
 Pulling a vacuum over the port hole can damage the device.
- <u>Do not board wash</u> after the reflow process. Board washing and cleaning agents can damage the device. Do not expose to ultrasonic processing or cleaning.
- Number of Reflow = recommend no more than 3 cycles.

11. ADDITIONAL NOTES

- (A) Packaging (reference SiSonic_Packaging_Spec.pdf)
- (B) Shelf life: Twelve (12) months when devices are to be stored in factory supplied, unopened ESD moisture sensitive bag under maximum environmental conditions of 30°C, 70% R.H.
- (C) Exposure: Devices should not be exposed to high humidity, high temperature environment. MSL (moisture sensitivity level) Class 2.
- (D) Out of bag: Maximum of 90 days out of ESD moisture sensitive bag, assuming maximum conditions of 30°C/70% R.H.





12. RELIABILITY SPECIFICATIONS

Note: After test conditions are performed, the sensitivity of the microphone shall not deviate more than 3dB from its initial value.

| Test | Description |
|------------------------------------|---|
| Thermal Shock | Microphone unit must operate when exposed to air-to-air thermal shock 100 cycles, from -40°C to +125°C. (IEC 68-2-4), |
| High Temperature Storage Test | Microphone unit must maintain sensitivity after storage at +105°C for 1,000 hours. (IEC 68-2-2 Test Ba) |
| Low Temperature Storage Test | Microphone unit must maintain sensitivity after storage at -40°C for 1,000 hours. (IEC 68-2-1 Test Aa) |
| High Temperature Operating Test | Microphone unit must operate within sensitivity specifications for 1,000 hours at 105°C. (IEC 68-2-2 Test Ba) |
| Low Temperature Operating Test | Microphone unit must operate within sensitivity specifications for 1,000 hours at – 40°C. (IEC 68-2-1 Test Aa) |
| Humidity Test | Tested under Bias at 85°C/85% R.H. for 1,000 hours. (JESD22-A101A-B) |
| Vibration Test | Microphone unit must operate under test condition: 4 cycles, from 20 to 2,000 Hz in each direction (x,y,z), 48 minutes, using peak acceleration of 20 G (+20%, -0%). (MIL 883E, method 2007.2, A) |
| Electrostatic Discharge | Tested to 8kV direct contact discharge to the case and tested to 2kV direct contact to I/O terminals. |
| Reflow | Microphone is tested to 5 passes through reflow oven, with microphone mounted upside-down under conditions of 260°C for 30 seconds maximum. |
| Mechanical Shock | Microphone must operate after exposure to shock test of 10,000 G per IEC 68-2-27, Ea. |





13. SPECIFICATION REVISIONS

| Revision | Detailed Specification Changes | Date |
|----------|--------------------------------|------|
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